

650V 25A Field Stop Trench IGBT

V _{CES}	650V
I _C	25A
V _{CE(sat) (Typ.)}	1.5V
P_{D}	165W

Outline LPDL (TO-263L) (1) (3)

Features

- 1) AEC-Q101 Qualified
- 2) Low Collector Emitter Saturation Voltage
- 3) Low Switching Loss & Soft Switching
- 4) Built in Very Fast & Soft Recovery FRD
- 5) Pb free Lead Plating; RoHS Compliant

Application

Automotive

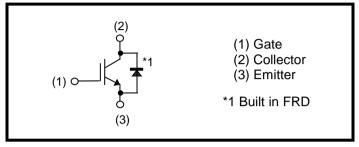
On & Off Board Chargers

DC-DC Converters

PFC

Industrial Inverter

●Inner Circuit



Packaging Specifications

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	Packaging	Taping			
	Reel Size (mm)	330			
Tuno	Tape Width (mm)	24			
Type	Basic Ordering Unit (pcs)	1,000			
	Packing Code	TL			
	Marking	RGW50NL65D			

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	650	V
Gate - Emitter Voltage		V_{GES}	±30	V
Collector Current	T _C = 25°C	I _C	57	А
Collector Current	T _C = 100°C	I _C	35	А
Pulsed Collector Current		I _{CP} *1	100	А
Diode Forward Current	T _C = 25°C	I _F	24	А
	T _C = 100°C	I _F	14	А
Diode Pulsed Forward Current		I _{FP} *1	100	А
Power Dissipation	T _C = 25°C	P _D	165	W
	T _C = 100°C	P _D	82	W
Operating Junction Temperature	Operating Junction Temperature		-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

^{*1} Pulse width limited by T_{imax.}

●Thermal Resistance

Parameter	Symbol	Values			Unit
raiametei 	Symbol	Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j\text{-c})}$	-	-	0.91	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	ı	ı	2.61	°C/W

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
r arameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_{C} = 10 \mu A, V_{GE} = 0 V$	650	ı	ı	V
Collector Cut - off Current	I _{CES}	$V_{CE} = 650V, V_{GE} = 0V$	-	-	10	μΑ
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V, V_{CE} = 0V$	ı	1	±200	nA
Gate - Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = 5V, I_{C} = 16.4 \text{mA}$	5.0	6.0	7.0	V
Collector - Emitter Saturation Voltage		$I_{C} = 25A, V_{GE} = 15V,$ $T_{j} = 25^{\circ}C$ $T_{j} = 175^{\circ}C$	-	1.5 1.85	1.9 -	V

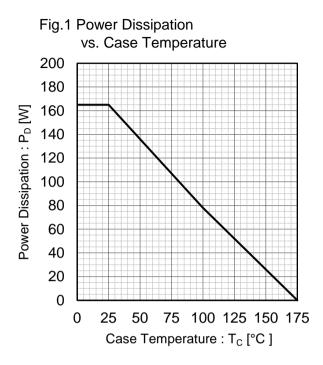
●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

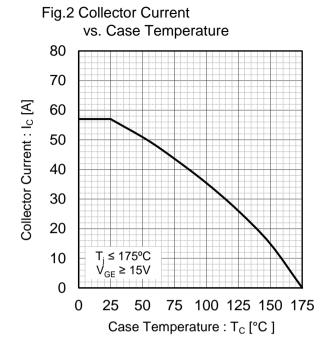
Parameter	Symbol	Conditions	Values			Unit
Parameter			Min.	Тур.	Max.	Offic
Input Capacitance	C _{ies}	$V_{CE} = 30V$,	-	2080	-	
Output Capacitance	C _{oes}	$V_{GE} = 0V$,	-	56	-	pF
Reverse transfer Capacitance	C _{res}	f = 1MHz	-	38	-	
Total Gate Charge	Q_g	V _{CE} = 400V,	-	73	-	
Gate - Emitter Charge	Q_{ge}	I _C = 25A,	-	15	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	28	-	1
Turn - on Delay Time	t _{d(on)}		-	31	-	
Rise Time	t _r	$I_C = 12.5A, V_{CC} = 400V,$ $V_{GE} = 15V, R_G = 10\Omega,$	-	7	-	ns
Turn - off Delay Time	t _{d(off)}	$T_i = 25^{\circ}C$	-	119	-	
Fall Time	t _f	Inductive Load	-	42	-	
Turn - on Switching Loss	E _{on}	*E _{on} include diode reverse recovery	-	0.11	-	m l
Turn - off Switching Loss	E _{off}	1000100100019	-	0.23	-	mJ
Turn - on Delay Time	t _{d(on)}		-	30	-	
Rise Time	t _r	$I_C = 12.5A, V_{CC} = 400V, V_{GF} = 15V, R_G = 10\Omega,$	-	7	-	20
Turn - off Delay Time	t _{d(off)}	$T_i = 175^{\circ}C$	-	130	-	ns
Fall Time	t _f	Inductive Load	-	64	-	
Turn - on Switching Loss	E _{on}	*E _{on} include diode reverse recovery	-	0.12	-	m l
Turn - off Switching Loss	E_{off}		-	0.28	-	mJ
Reverse Bias Safe Operating Area	RBSOA	$I_C = 100A$, $V_{CC} = 520V$, $V_P = 650V$, $V_{GE} = 15V$, $R_G = 100\Omega$, $T_j = 175^{\circ}C$	FU	LL SQUA	.RE	-

●FRD Electrical Characteristics (at T_j = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol		Min.	Тур.	Max.	Unit
	I _F = 12A,	I _F = 12A,				
Diode Forward Voltage	V _F	$T_j = 25^{\circ}C$	-	1.5	1.95	V
		T _j = 175°C	-	1.6	-	
Diode Reverse Recovery Time	t _{rr}	$I_F = 12.5A,$ $V_{CC} = 400V,$ $di_F/dt = 200A/\mu s,$ $T_j = 25^{\circ}C$	-	71	1	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	5.3	ı	А
Diode Reverse Recovery Charge	Q _{rr}		-	0.21	ı	μC
Diode Reverse Recovery Energy	Err		-	8.3	ı	μJ
Diode Reverse Recovery Time	t _{rr}	$I_F = 12.5A,$ $V_{CC} = 400V,$ $di_F/dt = 200A/\mu s,$ $T_j = 175^{\circ}C$	-	87	ı	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	5.8	ı	А
Diode Reverse Recovery Charge	Q _{rr}		-	0.27	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	11.8	-	μJ

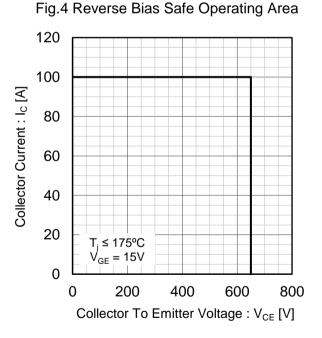
• Electrical Characteristic Curves





1000 1µs 100 Collector Current : I_C [A] 10µs 10 100µs 1 0.1 $T_{\rm C} = 25^{\rm o}{\rm C}$ Single Pulse 0.01 10 100 1000 Collector To Emitter Voltage: V_{CE} [V]

Fig.3 Forward Bias Safe Operating Area



•Electrical Characteristic Curves

Fig.5 Typical Output Characteristics

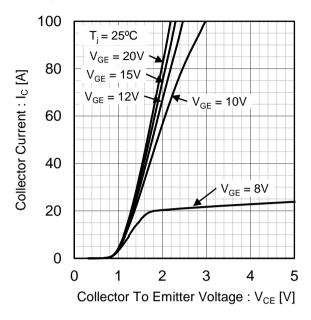


Fig.6 Typical Output Characteristics

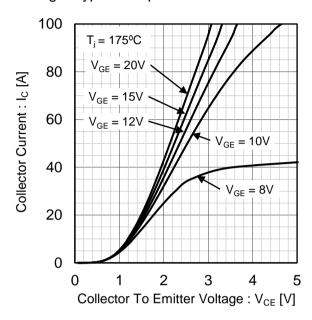


Fig.7 Typical Transfer Characteristics

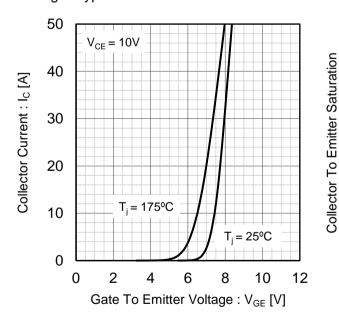
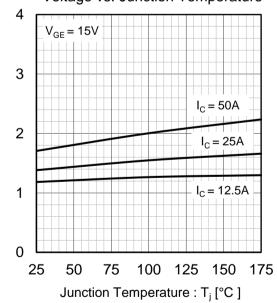


Fig.8 Typical Collector to Emitter Saturation Voltage vs. Junction Temperature



Voltage: V_{CE(sat)} [V]

Datasheet **RGW50NL65DHRBTL**

Collector To Emitter Saturation

Fig.9 Typical Collector to Emitter Saturation Voltage vs. Gate to Emitter Voltage 20 $T_i = 25^{\circ}C$ Collector To Emitter Saturation $I_{\rm C} = 50A$ 15 Voltage: V_{CE(sat)} [V] $I_C = 25A$ $I_{\rm C} = 12.5A$ 10 5 0 5 10 15 20 Gate To Emitter Voltage: VGE [V]

Fig.10 Typical Collector to Emitter Saturation Voltage vs. Gate to Emitter Voltage

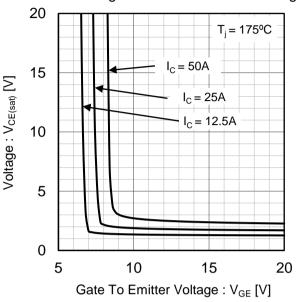
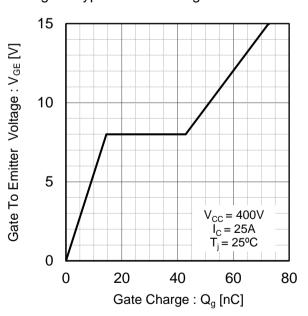


Fig.11 Typical Capacitance vs. Collector to Emitter Voltage 10000 $\boldsymbol{C}_{\text{ies}}$ 1000 Capacitance [pF] 100 Coes 10 $\mathsf{C}_{\mathsf{res}}$ f = 1MHz $V_{GE} = 0V$ = 25°C 0.01 0.1 1 10 100 Collector To Emitter Voltage: V_{CE} [V]

Fig.12 Typical Gate Charge



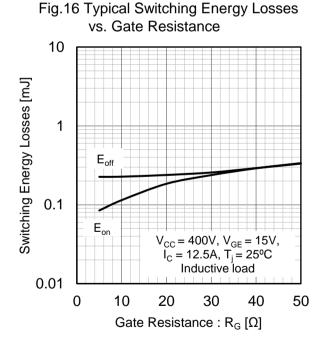
Electrical Characteristic Curves

Fig.13 Typical Switching Time vs. Collector Current 1000 Switching Time [ns] $t_{d(off)}$ 100 $t_{\rm f}$ $t_{d(on)}$ 10 $V_{CC} = 400V, V_{GE} = 15V,$ $R_{G} = 10\Omega, T_{j} = 25^{\circ}C$ Inductive load 1 0 10 20 30 40 50 Collecter Current : I_C [A]

vs. Gate Resistance 1000 $t_{d(off)}$ Switching Time [ns] 100 $t_{d(on)}$ 10 $V_{CC} = 400V, V_{GE} = 15V,$ $I_{C} = 12.5A, T_{j} = 25^{\circ}C$ Inductive load 1 0 10 20 30 50 Gate Resistance : $R_G[\Omega]$

Fig.14 Typical Switching Time

Fig.15 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] 1 $\mathsf{E}_{\mathsf{off}}$ 0.1 E_{on} V_{CC} = 400V, V_{GE} = 15V, R_G = 10 Ω , T_j = 25°C Inductive load 0.01 0 10 20 30 40 50 Collecter Current : I_C [A]





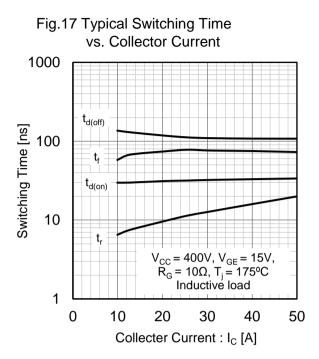


Fig.18 Typical Switching Time vs. Gate Resistance 1000 $t_{d(off)}$ Switching Time [ns] 100 $t_{d(on)}$ 10 $V_{CC} = 400V, V_{GE} = 15V,$ $I_{C} = 12.5A, T_{j} = 175^{\circ}C$ Inductive load 1 0 10 20 30 50 Gate Resistance : $R_G[\Omega]$

Fig.19 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] 1 $\mathsf{E}_{\mathsf{off}}$ 0.1 E_{on} $V_{CC} = 400V, V_{GE} = 15V,$ $R_G = 10\Omega, T_j = 175^{\circ}C$ Inductive load 0.01 0 10 20 30 40 50 Collecter Current : I_C [A]

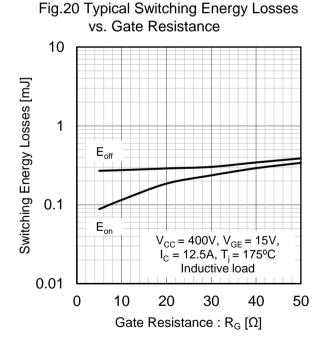


Fig.21 Typical Diode Forward Current vs. Forward Voltage

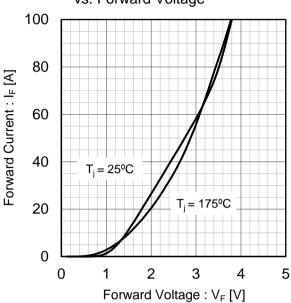


Fig.22 Typical Diode Revese Recovery Time vs. Forward Current

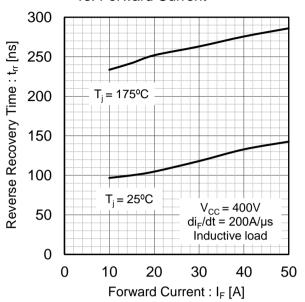


Fig.23 Typical Diode Reverse Recovery Current vs. Forward Current

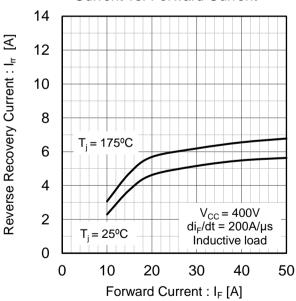


Fig.24 Typical Diode Rrverse Recovery Charge vs. Forward Current

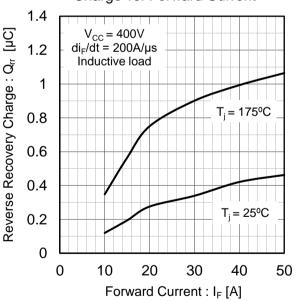


Fig.25 Typical IGBT Transient Thermal Impedance

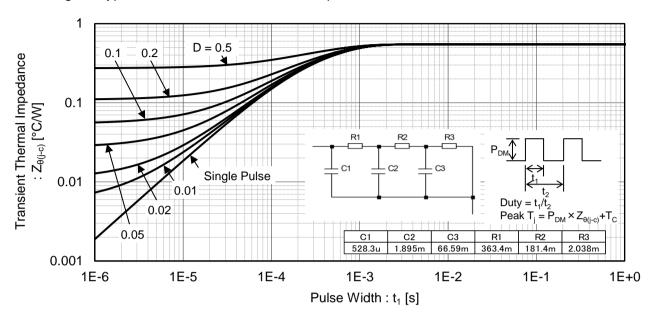
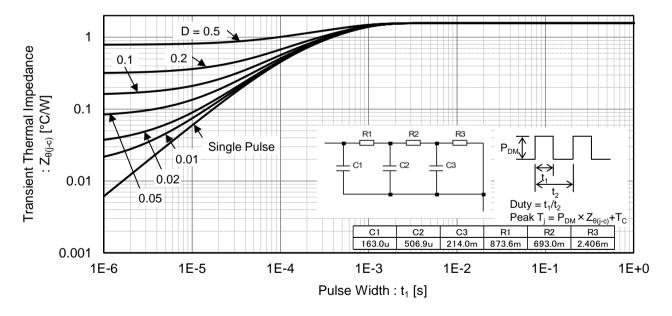


Fig.26 Typical Diode Transient Thermal Impedance



Datasheet **RGW50NL65DHRBTL**

●Inductive Load Switching Circuit and Waveform

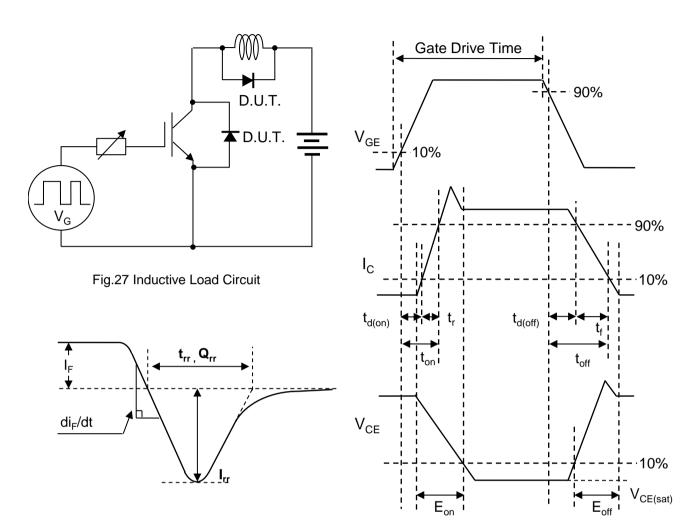


Fig.29 Diode Reverse Recovery Waveform

Fig.28 Inductive Load Waveform

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